Rev. 04/03

Docket No. <u>ELM-1 Cont. 15</u>

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant

Glenn J. Leedy

Application No.:

10/766,629 Confirmation No.: 3771

Filed

January 27, 2004

For

APPARATUS AND METHODS FOR MASKLESS PATTERN GENERATION

Group Art Unit: 1765

Examiner

: Not yet assigned

New York, New York July 19, 2004

Hon. Commissioner for Patents P.O. Box 1450

Alexandria, Virginia 22313-1450

TRANSMITTAL LETTER FOR INFORMATION DISCLOSURE STATEMENT

Sir:

Transmitted herewith is an Information Disclosure Statement in the above-identified application. This Statement is submitted:

- within three months of the application filing [] date:
- [X]more than three months from the application filing date but before the mailing date of the first Office Action on the merits.

In accordance with 37 C.F.R. § 1.97, submission of this Statement requires no fee. However, if for any reason a fee is due, the Director is hereby authorized to charge payment of any fees required in connection with this Information Disclosure Statement to Deposit Account

No. 06-1075. A duplicate copy of this letter is transmitted herewith.

Respectfully submitted,

Philip R. Poh

Registration No. 51,176 Agent for Applicants

FISH & NEAVE

Customer No. 1473

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I hereby certify that this Correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope

Addressed to:

Commissioner for Patents

P.O. Box 1450

- Alexandria, VA 22313-1450 on

Claire J. Sainti-Van Goodman

Signature of Person Signing

ELM-1 Cont. 15

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Glenn J. Leedy

Application No.: 10/766,629 Confirmation No.: 3771

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MASKLESS PATTERN GENERATION

Group Art Unit : 1765

Examiner : Not yet assigned

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Alexandrian, Virginia 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

In accordance with 37 C.F.R. §§ 1.56 and 1.97, applicant wishes to call the attention of the Examiner to the following documents:

U.S. Patents

Fujii et al.	Re. 34,893	04/04/95
Foster	2,915,722	12/01/59
Farrand	3,202,948	08/24/65
Lesk	3,559,282	02/02/71
Burkhardt	3,560,364	02/02/71
Emmasingel	3,602,982	09/07/71
Medicus	3,615,901	10/26/71
Napoli et al.	3,716,429	02/13/73
Krishna et al.	3,777,227	12/14/73
Kuipers	3,868,565	02/25/75
Yerman	3,922,705	11/25/75
Wanlass	3,997,381	12/14/76
Stein	4,070,230	01/24/78
Greenwood et al.	4,131,985	01/02/79
Hauser, Jr., et al.	4,142,004	02/27/79

		00/04/01
Hoeberechts	4,251,909	02/24/81
Kubacki	4,262,631	04/21/81
Shioya et al.	4,394,401	07/19/83
Trenkler et al.	4,401,986	08/30/83
		•
Thomas et al.	4,416,054	11/22/83
Takagi et al.	4,539,068	09/03/85
Reid et al.	4,585,991	04/29/86
Yasumoto et al.	4,612,083	09/16/86
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Belanger et al.	4,617,160	10/14/86
Shimizu et al.	4,618,397	10/21/86
Schmitz	4,618,763	10/21/86
Christensen	4,663,559	05/05/87
Burns et al.	4,684,436	08/04/87
Hatada	4,693,770	09/15/87
Maeda et al.	4,702,336	10/27/87
Seibert et al.	4,702,936	10/27/87
Go	4,706,166	11/10/87
Stevenson	4,721,938	01/26/88
Reid	4,761,681	08/02/88
Holmen et al.	4,784,721	11/15/88
Freeman	4,810,673	03/07/89
Mattox et al.	4,825,277	04/25/89
Tam et al.	4,857,481	08/15/89
Leedy	4,924,589	05/15/90
Borel et al.	4,940,916	07/10/90
Borel et al.	ReB14,940916	11/26/96
Vranish et al.	4,950,987	08/21/90
Lee et al.	4,952,446	08/18/90
Rokos	4,954,865	09/04/90
Shinomiya	4,957,882	09/18/90
Young et al.	4,965,415	10/23/90
-		
Mauger	4,966,663	10/30/90
Leedy	4,994,735	02/19/91
Keogh et al.	5,008,619	04/16/91
Allen et al.	5,010,024	04/23/91
	5,020,219	06/04/91
Leedy		
Leedy	5,034,685	07/23/91
Greenwald et al.	5,070,026	12/03/91
Findler et al.	5,071,510	12/10/91
Machado et al.	5,098,865	03/24/92
		•
Leedy	5,103,557	04/14/92
Mauger	5,110,373	05/05/92
Eichelberger	5,111,278	05/05/92
Chan et al.	5,116,777	05/26/92
Miller	5,130,894	07/14/92
Roy	5,132,244	07/21/92
Hadwin	5,151,775	09/29/92

	7	
Henager, Jr., et a		10/20/92
Zimmerman	5,203,731	04/20/93
Leedy	5,225,771	07/06/93
Bower et al.	5,236,118	08/17/93
Bureau et al.		11/16/93
	5,262,351	
Bertin et al.	5,270,261	12/14/93
Sanders	5,273,940	12/28/93
Tuckerman	5,274,270	12/28/93
Chebi et al.	5,279,865	01/18/94
Nakanishi et al.	5,284,796	02/08/94
Leedy	5,323,035	06/21/94
Wojnarowski	5,324,687	06/28/94
Leedy	5,354,695	10/11/94
MacDonald	5,363,021	11/08/94
Goossen	5,385,632	01/31/95
Nelson et al.	5,385,909	10/25/94
		05/30/95
Shimoji	5,420,458	• •
Miyake	5,424,920	06/13/95
Finnila	5,426,072	06/20/95
Akagi et al.	5,426,363	06/20/95
Yasohama et al.	5,432,444	07/11/95
Carson et al.	5,432,729	07/11/95
Hauck et al.	5,434,500	07/18/95
Leedy	5,451,489	09/19/95
Leedy	5,453,404	09/26/95
Gurtler et al.	5,457,879	10/17/95
Naruse	5,476,813	12/19/95
Gates	5,489,554	02/06/96
Bertin et al.	5,502,667	03/26/96
Leedy		04/30/96
_	5,512,397	
Pati et al.	5,527,645	06/18/96
Koskenmaki et al.	5,529,829	06/25/96
Frye et al.	5,534,465	07/09/96
Toshiaki et al.	5,555,212	09/10/96
Ramm et al.	5,563,084	10/08/96
Leedy	5,571,741	11/05/96
Leedy	5,580,687	12/03/96
Ludwig et al.	5,581,498	12/03/96
Pierrat	5,582,939	12/10/96
Hornbeck	5,583,688	12/10/96
Leedy	5,592,007	01/07/97
Leedy	5,592,018	01/07/97
_		
Heijboer	5,595,933	01/27/97
Noda	5,606,186	02/25/97
Tennant et al.	5,627,112	05/06/97
Leedy	5,629,137	05/13/97
Leedy	5,633,209	05/27/97
-	•	•

Val	5,637,536	06/10/97
Leedy	5,654,127	08/05/97
Leedy	5,654,220	08/05/97
Hudak et al.	5,656,552	08/12/97
Chen et al.	5,675,185	10/07/97
Ohara et al.	5,694,588	12/02/97
Leedy	5,725,995	03/10/98
Weise et al.	5,750,211	05/12/98
Bozso et al.	5,760,478	06/02/98
Okonogi	5,773,152	06/30/98
Rolfson	5,786,116	07/28/98
Zavracky et al.	5,793,115	08/11/98
Ray	5,831,280	11/03/98
Leedy	5,834,334	11/10/98
Leedy	5,840,593	11/24/98
Ito et al.	5,856,695	01/05/99
Sotokawa et al.	5,868,949	02/09/99
Leedy	5,869,354	02/09/99
Sweatt et al.	5,870,176	02/09/99
Davidson	5,880,010	03/09/99
Field et al.	5,882,532	03/16/99
Hübner	5,902,118	05/11/99
Leedy	5,915,167	06/22/99
Leedy	5,946,559	08/31/99
Leedy	5,985,693	11/16/99
Cutter et al.	5,998,069	12/07/99
Leedy	6,008,126	12/28/99
Leedy	6,020,257	02/01/00
Houston	6,045,625	04/04/00
Adamic, Jr.	6,084,284	07/04/00
Gardner et al.	6,097,096	08/01/00
Leedy	6,133,640	10/17/00
Tayanaka	6,194,245 B1	02/27/01
Aleshin et al.	6,197,456 B1	03/06/01
Leedy	6,208,545 B1	03/27/01
Patti	6,236,602 B1	05/22/01
Lin	6,261,728 B1	07/17/01
Leedy	6,288,561 B1	09/11/01
Leedy	6,294,909 B1	09/11/01

Foreign Patents

PCT	WO 98/19337	05/1998
UK	GB 2,215,168	09/1989
EPO	EP 0 189 976	08/1986
EPO	EP 0 731 525	09/1996
FRANCE	2641129	12/1988

JAPAN	JP 60-7464	3 04/1985
JAPAN	JP 02-0825	64 03/1990
JAPAN	JP 04-0833	71 03/1992
JAPAN	JP 04-1079	64 04/1992
JAPAN	JP 4020276	00A 01/1990

Other Documents

"IC Tower Patent: Simple Technology Receives Patent on the IC Tower, a Stacked Memory Technology," http://www.simpletech.com/whatsnew/memory/@60824.htm (1998).

Alloert, K., et al., "A Comparison Between Silicon Nitride Films Made by PCVD of N_2 -SiH₄ /A_r and N_2 -SiH₄/He," Journal of the Electrochemical Society, Vol. 132, No. 7, pp. 1763-1766, (July 1985).

Hendricks, et al., "Polyquinoline Coatings and Films: Improved Organic Dielectrics for IC's and MCM's," Eleventh IEEE/CHMT International Electronics Manufacturing Technology Symposium, "pp. 361-265 (1991).

Knolle, W.R., et al., "Characterization of Oxygen-Doped, Plasma-Deposited Silicon Nitride," Journal of the Electrochemical Society, Vol. 135, No. 5, pp. 1211-1217, (May 1988).

Nguyen, S.V., "Plasma Assisted Chemical Vapor Deposited Thin Films for Microelectronic Applications, J. Vac. Sci. Technol. Vol. B4, No. 5, pp.1159-1167, (Sep/Oct. 1986).

Olmer, et al., "Intermetal Dielectric Deposition by Plasma Enhanced Chemical Vapor Deposition," Fifth IEEE/CHMT International Electronic Manufacturing Technology Symposium - Design-to-Manufacturing Transfer Cycle," pp. 98-99 (1988).

Runyan, W.R., "Deposition of Inorganic Thin Films," Semiconductor Integrated Circuit Processing Technology, p. 142 (1990).

Sze, S.M., "Surface Micromachining," Semiconductor Sensors, pp. 58-63 (1994).

Vossen, John L., "Plasma-Enhanced Chemical Vapor Deposition," Thin Film Processes II, pp. 536-541 (1991).

Wolf, Stanley, "Basic of Thin Films," Silicon Processing for the VLSI Era, pp. 115, 192-193 and 199 (1986).

Copies of the aforementioned documents are listed on the accompanying Form PTO-1449 (submitted in duplicate).

It is respectfully requested that these documents be:

(1) fully considered by the Patent and Trademark Office

during the examination of this application; and (2) printed

on any patent which may issue on this application.

Applicant requests that a copy of Form PTO-1449, as

considered and initialized by the Examiner, be returned with

the next communication.

Consideration of the foregoing in relation to this patent application is respectfully requested.

Respectfully submitted,

Philip R. Poh

Registration No. 51,176

Agent for Applicant

FISH & NEAVE

Customer No. 1473

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Tel.: (212) 596-9000

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P.O. Box 1450 Alexandria, VA 22313-1450 on

Claire J. Saidtil van Goodman

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JUL 2 1 2004 S

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

NFORMATION DISCLOSURE STATEMENT BY APPLICANT

ATTY. DOCKET NO. ELM-1 Cont. 15	APPLICATION NO. 10/766,629
APPLICANT Glenn J. Leedy	CONFIRMATION NO. 3771
FILING DATE January 27, 2004	GROUP 1765

U.S. PATENT DOCUMENTS

EXAMINE	DOCUMENT		U.S. PATENT DOCUMENT		aupai saa	FILING DATE
R INITIAL	NUMBER	DATE	NAME	CLASS	SUBCLASS	IF APPROPRIATE
	Re. 34,893	04/04/95	Fujii et al.	257	419	
	2,915,722	12/01/59	Foster	336	115	
	3,202,948	08/24/65	Farrand	336	115	
	3,559,282	02/02/71	Lesk	438	113	
	3,560,364	02/02/71	Burkhardt	324	207.12	
	3,602,982	09/07/71	Emmasingel	29	577	
	3,615,901	10/26/71	Medicus	148	11.5 R	
\	3,716,429	02/13/73	Napoli et al.	156	17	
	3,777,227	12/14/73	Krishna et al.	257	578	
	3,868,565	02/25/75	Kuipers	324	207.26	
	3,922,705	11/25/75	Yerman	357	26	
	3,997,381	12/14/76	Wanlass	156	3	
,	4,070,230	01/24/78	Stein	156	657	
	4,131,985	01/02/79	Greenwood et al.	29	580	
	4,142,004	02/27/79	Hauser, Jr. et al.	438	792	
	4,251,909	02/24/81	Hoeberechts	29	580	
	4,262,631	04/21/81	Kubacki	118	723MP	
·	4,394,401	07/19/83	Shioya et al.	427	574	
	4,401,986	08/30/83	Trenkler et al.	340	870.32	
	4,416,054	11/22/83	Thomas et al.	29	572	
	4,539,068	09/03/85	Takagi et al.	156	614	
	4,585,991	04/29/86	Reid et al.	324	158 P	
	4,612,083	09/16/86	Yasumoto et al.	156	633	
	4,617,160	10/14/86	Belanger et al.	264	40.1	
	4,618,397	10/21/86	Shimizu et al.	156	628	
	4,618,763	10/21/86	Schmitz	250	211R	
	4,663,559	05/05/87	Christensen	313	336	
	4,684,436	08/04/87	Burns et al.	216	65	
	4,693,770	09/15/87	Hatada	156	151	

EXAMINER

FORM PTO-1449			OF COMMERCE DEMARK OFFICE	ATTY. DOO ELM-1 Con		APPLICATION NO. 10/766,629	
	FORMATION D			APPLICANT Glenn J. Leed		CONFIRMATION NO 3771	
STATEMENT DI ALI EN		APPLIC	ANI	FILING DA January 27		GROUP 1765	
4,702,	336 10/	27/87	Maeda et al.	180	197		
4,702,		27/87	Seibert et al.	427	583		
4,706,		10/87	Go	361	403		
4,721,	938 01/	26/88	Stevenson	338	4		
4,761,	681 08/	02/88	Reid	357	68		
4,784,	721 11/	15/88	Holmen et al.	156	647		
4,810,0	673 03/	07/89	Freeman	438	386		
4,825,3	277 04/	25/89	Mattox et al.	257	639		
4,857,4	481 08/	15/89	Tam et al.	438	619		
4,924,	589 05/	15/90	Leedy	438	6		
4,940,9	916 07/	10/90	Borel et al.	313	306		
Re B1	4,940,916 11/	26/96	Borel et al.	315	306		
4,950,9		21/90	Vranish et al.	324	207.23		
4,952,		18/90	Lee et al.	428	220		
4,954,8	365 09/	04/90	Rokos	257	378		
4,957,8	382 09/	18/90	Shinomiya	438	65		
4,965,4		23/90	Young et al.	200	83 N		
4,966,0	663 10/	30/90	Mauger	205	656		
4,994,	735 02/	19/91	Leedy	324	158		
5,008,0	619 04/	16/91	Keogh et al.	324	207.17		
5,010,0	024 04/	23/91	Allen et al.	438	659		
5,020,2	219 06/	04/91	Leedy	29	846		
5,034,0	685 07/	23/91	Leedy	324	158 F		
5,070,0	026 12/	03/91	Greenwald et al.	437	3		
5,071,	510 12/	10/91	Findler et al.	156	647		
5,098,8		24/92	Machado et al.	438	788		
5,103,		14/92	Leedy	29	832		
5,110,	1	05/92	Mauger	148	33.2		
5,111,2		05/92	Eichelberger	357	75		
5,116,		26/92	Chan et al.	438	234		
5,130,8		14/92	Miller	361	393		
5,132,2	244 07/	21/92	Roy	438	477		

FORM PTO-1449		T OF COMMERCE DEMARK OFFICE	ATTY. DOC ELM-1 Con		APPLICATION NO. 10/766,629	
	INFORMATION DISCLOSURE STATEMENT BY APPLICANT			r edy	CONFIRMATION NO 3771	
	STATEMENT BY APPLICANT		FILING DAT January 27,		GROUP 1765	
5,151,	775 09/29/92	Hadwin	357	80		
5,156,	909 10/20/92	Henager, Jr. et al.	428	334		
5,203,	731 04/20/93	Zimmerman	445	24		
5,225,	771 07/06/93	Leedy	324	158		
5,236,	118 08/17/93	Bower et al.	228	193		
5,262,	351 11/16/93	Bureau et al.	437	183		
5,270,	261 12/14/93	Bertin et al.	437	209		
5,273,	940 12/28/93	Sanders	437	209		
5,274,	270 12/28/93	Tuckerman	257	758		
5,279,	865 01/18/94	Chebi et al.	427	574		
5,284,	796 02/08/94	Nakanishi et al.	437	183		
5,323,0	035 06/21/94	Leedy	257	48		
5,324,0	687 06/28/94	Wojnarowski	437	225		
5,354,0	695 10/11/94	Leedy	438	411		
5,363,0	021 11/08/94	MacDonald	315	366		
5,385,9	909 01/31/95	Nelson et al.	514	291		
5,385,6	632 01/31/95	Goossen	156	630		
5,420,4	458 05/30/95	Shimoji	257	622		
5,424,9	920 06/13/95	Miyake	361	735		
5,426,0	072 06/20/95	Finnila	437	208		
5,426,3	363 06/20/95	Akagi et al.	324	239		
5,432,4	444 07/11/95	Yasohama et al.	324	240	_	
5,432,		Carson et al.	365	63		
5,434,	500 07/18/95	Hauck et al.	324	67		
5,451,4	489 09/19/95	Leedy	430	313		
5,453,4	404 09/26/95	Leedy	437	203		
5,457,8	879 10/17/95	Gurtler et al.	29	895		
5,476,8	813 12/19/95	Naruse	437	132		
5,489,	554 02/06/96	Gates	437	208		
5,502,6		Bertin et al.	365	51		
5,512,3	397 04/30/96	Leedy	430	30		
5,527,6	645 06/18/96	Pati et al.	430	5		

FORM PTO-1449		NT OF COMMERCE RADEMARK OFFICE	ATTY. DOC ELM-1 Cont		APPLICATION NO. 10/766,629	
	FORMATION DISCL		APPLICANT Glenn J. Leedy		CONFIRMATION NO. 3771	
		LICANI	FILING DAT January 27,		GROUP 1765	
5,529,	829 06/25/9	6 Koskenmaki et al.	428	167		
5,534,	465 07/09/9	Frye et al.	437	209		
5,555,			365	200		
5,563,	084 10/08/9	Ramm et al.	437	51		
5,571,		6 Leedy	437	51		
5,580,			430	5		
5,581,			365	63		
5,582,			430	5		
5,583,		3 Hornbeck	359	291		
5,592,		7 Leedy	257	347		
5,592,		7 Leedy	257	619		
5,595,	933 01/21/9	7 Heijboer	439	20		
5,606,			257	226		
5,627,		7 Tennant et al.	438	113		
5,629,		7 Leedy	430	313		
5,633,		7 Leedy	435	228		
5,637,			438	686		
5,654,		7 Leedy	430	315		
5,654,	220 08/05/9	7 Leedy	438	25		
5,656,	552 08/12/9	7 Hudak et al.	438	15		
5,675,		7 Chen et al.	257	774		
5,694,		7 Ohara et al.	395	566		
5,725,			430	315		
5,750,			427	579		
5,760,			257	777		
5,773,			428	446		
5,786,			430	5		
5,793,			257	777		
5,831,			257	48		
5,834,			438	107		
5,840,			438	6		
5,856,			257	370		

FORM PTO-1	FORM PTO-1449 U.S. DEPART PATENT AND					ATTY. DO		APPLICATIO 10/766,629	N NO.	
	INFORMATION STATEMENT					APPLICAN Glenn J. Le		CONFIRMAT 3771	CONFIRMATION NO. 3771	
	STATEMEN	IDIAP	PLICA	MN I		FILING DA January 27		GROUP 1765		
	5,868,949	02/09/	99	Sotokaw	a et al.	216	18			
	5,869,354	02/09/	99 1	Leedy		438	110			
	5,870,176	02/09/		Sweatt e	t al.	355	53		-	
	5,880,010	03/09/	99	Davidsor	า	438	455			
	5,882,532	03/16/	99	Field et a	al.	216	2			
	5,902,118	05/11/	99 1	Hübner		438	106			
	5,915,167 06/22/5 5,946,559 08/31/5 5,985,693 11/16/5 5,998,069 12/07/5 6,008,126 12/28/5			Leedy		438	108			
				Leedy		438	157			
				Leedy		438	107			
							5			
							667			
	6,020,257	02/01/	00	Leedy		438	626			
	6,045,625	04/04/00		Houston		148	33.3			
	6,084,284	07/04/	/00 Adamic, J	07/04/00 Adamic, Jr. 08/01/00 Gardner et al.	Jr.	257	506			
	6,097,096	08/01/	08/01/00 Gardner		257	257 777				
	6,133,640	10/17/			Leedy		257 778			
	6,194,245 B1	02/27/	01			438	57			
	6,197,456 B1	03/06/	6/01 Aleshin et al. 7/01 Leedy		430	5				
	6,208,545 B1	03/27/				365	51			
	6,236,602 B1	05/22/				365	201			
	6,261,728 B1	07/17/	01				30			
	6,288,561 B1	09/11/	01	Leedy		324	760			
	6,294,909 B1	09/25/	01			324	207.17			
			FOF	REIGN P	ATENT DOCUM	MENTS				
EXAMINER INITIAL				ATE	COUNTRY	CLASS	SUBCLA	SS TRANS	NO NO	
	WO 98/19337		05/1	998	PCT	H01L	21/44			
	GB 2,215,168		09/1		UK	G09G	1/00			
	EP 0 189 976	-	08/1		EPO	H01L	31/18			
	EP 0 731 525		09/1		EPO	H01P	5/00			
	2641129		12/1		France	H01L	39/04			
	JP 60-74643		04/1		Japan			ABST		

FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE			1	ATTY. DOCKET NO. ELM-1 Cont. 15		APPLICATION NO. 10/766,629			
INFORMATION DISCLOSURE STATEMENT BY APPLICANT					APPLICANT Glenn J. Leedy		CONFIRMATION NO. 3771		
					FILING DATE January 27, 2004		GROUP 1765		
					W				
JP	02-082564	03/1990	Japan				ABST		
JP	04-083371	03/1992	Japan				ABST		
JP	04-107964	04/1992	Japan				ABST		
JP	402027600A	01/1990	Japan				ABST		

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER INITIAL	
	"IC Tower Patent: Simple Technology Receives Patent on the IC Tower, a Stacked Memory Technology," http://www.simpletech.com/whatsnew/memory/@60824.htm (1998).
	Alloert, K., et al., "A Comparison Between Silicon Nitride Films Made by PCVD of N_2 -SiH ₄ /Ar and N_2 -SiH ₄ /He," <i>Journal of the Electrochemical Society</i> , Vol. 132, No. 7, pp. 1763-1766, (July 1985).
	Hendricks, et al., "Polyquinoline Coatings and Films: Improved Organic Dielectrics for IC's and MCM's," Eleventh IEEE/CHMT International Electronics Manufacturing Technology Symposium," pp. 361-265 (1991).
	Knolle, W.R., et al., "Characterization of Oxygen-Doped, Plasma-Deposited Silicon Nitride," <i>Journal of the Electrochemical Society</i> , Vol. 135, No. 5, pp. 1211-1217, (May 1988).
	Nguyen, S.V., "Plasma Assisted Chemical Vapor Deposited Thin Films for Microelectronic Applications, J. Vac. Sci. Technol. Vol. B4, No. 5, pp.1159-1167, (Sep/Oct. 1986).
	Olmer, et al., "Intermetal Dielectric Deposition by Plasma Enhanced Chemical Vapor Deposition," Fifth IEEE/CHMT International Electronic Manufacturing Technology Symposium - Design-to-Manufacturing Transfer Cycle," pp. 98-99 (1988).
	Runyan, W.R., "Deposition of Inorganic Thin Films," Semiconductor Integrated Circuit Processing Technology, p. 142 (1990).
	Sze, S.M., "Surface Micromachining," Semiconductor Sensors, pp. 58-63 (1994).
	Vossen, John L., "Plasma-Enhanced Chemical Vapor Deposition," <i>Thin Film Processes II</i> , pp. 536-541 (1991).
	Wolf, Stanley, "Basics of Thin Films," Silicon Processing for the VLSI Era, pp. 115, 192, 193, and 199 (1986).